

ABSTRACT

This invention relates to a process for manufacturing an anisotropic conducting film comprising a layer of electrically insulating material and conducting through inserts, the said process comprising
5 the following steps:

a) formation on a substrate of at least one layer of material with through holes, the said layer being called the perforated layer,

b) filling of the through holes to form conducting
10 inserts. The process also comprises production of a mask partially covering a first end of the conducting inserts and etching of the unmasked part of the ends of the conducting inserts so as to obtain conducting inserts with pointed ends.

15 The invention is applicable to the formation of components (chips, integrated circuits) with a high interconnections density.